

The Law Offices of Mikio Ishimaru

Intellectual Property Law
Patents - Licensing - Strategy - & Related Matters
1110 Sunnyvale-Saratoga Road, Suite A1
Sunnyvale, CA 94087
Telephone: (408) 738-0592
Fax: (408) 738-0881

**RECEIVED
CENTRAL FAX CENTER**

FEB 12 2004

OFFICIAL**Fax**

To:	Commissioner of Patents	From:	Mikio Ishimaru
Fax:	(703) 872-9306	Pages:	10
Phone:		Date:	February 10, 2004
Re:	U.S. Patent Application Serial No. 10/055,094	CC:	Attorney Docket No.: ST01-006

☒ Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address

IMPORTANT

The information contained in this facsimile is intended only for the use of the individual or entity to whom it is addressed. If you are not the intended recipient, you are hereby notified that any use, dissemination, distribution or copying of this communication is strictly prohibited. If you have received this facsimile in error, please immediately notify us by telephone, and return the original message to us at the address above via the U.S. Postal Service. Thank you.

For confirmation or assistance, call (408) 738-0592

Certificate of Transmission under 37 CFR 1.8

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office

on February 10, 2004


Tamara Tucker

The following documents are being submitted:

Request and Transmittal

Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address

Statement under 37 CFR 3.73(b)

**RECEIVED
CENTRAL FAX CENTER**

FEB 12 2004

OFFICIAL

Attorney Docket No: ST01-006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial Number 10/055,094
Filing Date 1/23/2002
Name of Patentee IL Kwon Shim
Title of Invention HEAT SPREADER ANCHORING & GROUNDING METHOD &
THERMALLY ENHANCED PBGA PACKAGE USING THE SAME

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**TRANSMITTAL AND REQUEST FOR REVOCATION OF POWER OF ATTORNEY
WITH NEW POWER OF ATTORNEY AND CHANGE OF CORRESPONDENCE
ADDRESS**

Dear Sir or Madam:

The applicant respectfully requests that all previous Powers of Attorney be revoked and the office appoint Mikio Ishimaru and all practitioners associated with Customer No. 22898.

Please also change the correspondence address for the above-identified application, U.S. Serial No. 10/055,094 to the address associated with Customer No. 22898.

Assignee of Record is the owner of the entire interest and submits the enclosed Statement under 37CFR 3.73(b).

Enclosed are the following:

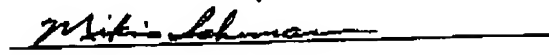
- ☒ Revocation of Power of Attorney with New Power of Attorney and Change of Correspondence Address
- ☒ Statement Under 37 CFR 3.73(b)
- ☒ Certificate of Transmission

Docket Number: ST01-006

Patent

Please charge any shortage in fees due in connection with the filing of this paper to Deposit Account No. 50-0374 and credit any excess fees to such deposit account.

Respectfully submitted,



Mikio Ishimaru
Reg. No. 27,449
February 10, 2004

The Law Offices of Mikio Ishimaru
1110 Sunnyvale-Saratoga Road, Suite A1
Sunnyvale, CA 94087

**REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND
CHANGE OF CORRESPONDENCE ADDRESS**

On behalf of ST Assembly Test Services Pte Ltd, I hereby revoke all previous powers of attorney given in the following U.S. Patents applications:

1. ☐
In re application of: Sum Kai Wah, Tan Wee Boon, and Jap Liop Jin
Serial No.: 10/054,423 Filing Date: 1/22/2002
Title: MULTI-PACKAGE CONVERSION KIT FOR A PICK AND PLACE HANDLER

- The single, original paper is filed for the above patent applications and the public is authorized to inspect and copy the original paper pursuant to 37 CFR 1.12(b).

2. ☒
In re application of: IL Kwon Shim, Hermes T. Apale, Weddie Racio Aquien, Dario S. Filoteo Jr., Virgil Cotoco Ararao, and Leo Merilo
Serial No.: 10/055,094 Filing Date: 1/23/2002
Title: HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING THE SAME

3. ☐
In re application of: Weddie Racio Aquien, Loreto Y. Cantillep, and Setho Sing Fee
Serial No.: 10/099,284 Filing Date: 3/15/2002
Title: HEAT SPREADER HOLE PIN 1 INDENTIFIER

4. ☐
In re application of: Rajiv Mehta, Liop-Jin Yap, Raymundo M. Camenforte, and Chee-Keong Tan
Serial No.: 10/140,573 Filing Date: 5/8/2002
Title: TESTING OF BGA AND OTHER CSP PACKAGES USING PROBING TECHNIQUES

5. ☐
In re application of: Virgil Cotoco Ararao, Hermes T. Apale, and IL Kwon Shim
Serial No.: 10/315,533 Filing Date: 12/10/2002
Title: MOLD CAP ANCHORING METHOD FOR MOLDED FLEX BGA PACKAGES

6. ☐
In re application of: IL Kwon Shim, Seng Guan Chow, and Gerry Balanon
Serial No.: 10/462,288 Filing Date: 6/16/2003
Title: PBGA SUBSTRATE FOR ANCHORING HEAT SINK

7. ☐
In re application of: John Briar
Serial No.: 10/043,605 Filing Date: 1/14/2002
Title: DISPOSABLE MOLD RUNNER GATE FOR SUBSTRATE BASED ELECTRONIC PACKAGES

REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND CHANGE OF
CORRESPONDENCE ADDRESS

8. ☐
In re application of: Tonglong Zhang and John Briar
Serial No.: 09/726,260 Filing Date: 11/30/2000
Title: EXTENDED LEAD PACKAGE
9. ☐
In re application of: IL Kwon Shim, Kambhampati Ramakrishna, and Seng Guan Chow
Serial No.: 10/256,407 Filing Date: 9/27/2002
Title: LEADFRAME FOR DIE STACKING APPLICATIONS AND
RELATED DIE STACKING CONCEPTS
10. ☐
In re application of: Raymundo M. Camenforte, Dioscoro A. Merilo, and Seng Guan Chow
Serial No.: 10/339,158 Filing Date: 1/9/2003
Title: SUPER THIN/SUPER THERMAL BALL GRID ARRAY PACKAGE
11. ☐
In re application of: John Briar
Serial No.: 09/640,534 Filing Date: 8/17/2000
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE
STRUCTURE
12. ☐
In re application of: John Briar
Serial No.: 10/693,217 Filing Date: 10/24/2003
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE
STRUCTURE
13. ☐
In re application of: Raymundo M. Camenforte and John Briar
Serial No.: 10/371,515 Filing Date: 2/20/2003
Title: SINGLE UNIT AUTOMATED ASSEMBLY OF FLEX ENHANCED
GRID ARRAY PACKAGES
14. ☐
In re application of: Weddie Racio Aquien, John Briar, and Setho Sing Fee
Serial No.: 10/323,447 Filing Date: 12/19/2002
Title: ENHANCED BGA GROUNDED HEATSINK
15. ☐
In re application of: Loreto Y. Cantillep
Serial No.: 10/236,579 Filing Date: 9/6/2002
Title: PBGA SINGULATED SUBSTRATE FOR MODEL MELAMINE
CLEANING
16. ☐
In re application of: Jeffrey D. Punzalan, Tan Hien Boon, Zheng Zheng, Jae Hak Yee, and
Byung Joon Han
Serial No.: 10/462,264 Filing Date: 6/16/2003
Title: GROUND PLANE FOR EXPOSED PACKAGE

REVOCATION OF POWER OF ATTORNEY WITH NEW POWER OF ATTORNEY AND CHANGE OF
CORRESPONDENCE ADDRESS17. ☐

In re application of: IL Kwon Shim, Hermes T. Apale, and Gerry Balanon
Serial No.: 10/119,920 Filing Date: 4/10/2002
Title: HEAT SPREADER INTERCONNECT METHODOLOGY FOR
THERMALLY ENHANCED PBGA PACKAGES

18. ☐

In re application of: Jian Jun Li
Serial No.: 10/224,151 Filing Date: 8/20/2002
Title: TEST COUPON PATTERN DESIGN TO CONTROL
MULTILAYER SAW SINGULATED PLASTIC BALL GRID
ARRAY SUBSTRATE MIS-REGISTRATION

19. ☐

In re application of: Yong Gang Jin and Won Sun Shin
Serial No.: 10/151,977 Filing Date: 5/21/2002
Title: TORCH BUMP

20. ☐

In re application of: IL Kwon Shim, Jian Jun Li, and Sheila Marie L. Alvarez
Serial No.: 10/279,900 Filing Date: 10/24/2002
Title: COST EFFECTIVE SUBSTRATE FABRICATION FOR FILP-CHIP
PACKAGES

- ☒ I hereby appoint Mikio Ishimaru and all practitioners associated with Customer
Number 22898
- ☒ Please change the Correspondence Address for the above identified Patents and
Applications to the address associated with Customer Number 22898
- ☒ Assignee of record is owner of the entire interest (see 37 CFR 3.71(b)), and submits
the enclosed Statement under 37 CFR 3.73(b).

The undersigned (whose title is supplied below) is empowered to sign below on behalf of the
Assignee.

February 3, 2004

Date


SignatureTan Lay Koon

Typed or printed name

President & CEO

Title

STATEMENT UNDER 37 CFR 3.73(b)

ST Assembly Test Services Pte Ltd, a Singapore corporation states that it is the assignee of the entire right, title, and interest of the patent applications identified below by virtue of the chain of title from the inventors to the current assignee as shown below:

1. ☐
Inventors: Sum Kai Wah, Tan Wee Boon, and Jap Liop Jin
Serial No.: 10/054,423 Filing Date: 1/22/2002
Title: MULTI-PACKAGE CONVERSION KIT FOR A PICK AND PLACE HANDLER
Chain of Title: From: Wah et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012547/0179

The single, original paper is filed for the above patent application and the public is authorized to inspect and copy the original paper pursuant to 37 CFR 1.12(b).
2. ☒
Inventors: IL Kwon Shim, Hermes T. Apale, Weddie Racio Aquien, Dario S. Filoteo Jr., Virgil Cotoco Ararao, and Leo Merilo
Serial No.: 10/055,094 Filing Date: 1/23/2002
Title: HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING THE SAME
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012560/0078
3. ☐
Inventors: Weddie Racio Aquien, Loreto Y. Cantillep, and Setho Sing Fee
Serial No.: 10/099,284 Filing Date: 3/15/2002
Title: HEAT SPREADER HOLE PIN 1 IDENTIFIER
Chain of Title: From: Aquien et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011013/0053
4. ☐
Inventors: Rajiv Mehta, Liop-Jin Yap, Raymundo M. Camenforte, and Chee-Keong Tan
Serial No.: 10/140,573 Filing Date: 5/8/2002
Title: TESTING OF BGA AND OTHER CSP PACKAGES USING PROBING TECHNIQUES
Chain of Title: From: Mehta et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 9782/0373

STATEMENT UNDER 37 CFR 3.73(b)

5. ☐
Inventors: Virgil Cotoco Ararao, Hermes T. Apale, and IL Kwon Shim
Serial No.: 10/315,533 Filing Date: 12/10/2002
Title: MOLD CAP ANCHORING METHOD FOR MOLDED FLEX BGA PACKAGES
Chain of Title: From: Ararao et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 013572 / 0799
6. ☐
Inventors: IL Kwon Shim, Seng Guan Chow, and Gerry Balanon
Serial No.: 10/462,288 Filing Date: 6/16/2003
Title: PBGA SUBSTRATE FOR ANCHORING HEAT SINK
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012212/0615
7. ☐
Inventor: John Briar
Serial No.: 10/043,605 Filing Date: 1/14/2002
Title: DISPOSABLE MOLD RUNNER GATE FOR SUBSTRATE BASED ELECTRONIC PACKAGES
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 9203/0956
8. ☐
Inventors: Tonglong Zhang and John Briar
Serial No.: 09/726,260 Filing Date: 11/30/2000
Title: EXTENDED LEAD PACKAGE
Chain of Title: From: Zhang et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 9296/0271
9. ☐
Inventors: IL Kwon Shim, Kambhampati Ramakrishna, and Seng Guan Chow
Serial No.: 10/256,407 Filing Date: 9/27/2002
Title: LEADFRAME FOR DIE STACKING APPLICATIONS AND RELATED DIE STACKING CONCEPTS
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 013348/0051
10. ☐
Inventors: Raymundo M. Camenforte, Dioscoro A. Merilo, and Seng Guan Chow
Serial No.: 10/339,158 Filing Date: 1/9/2003
Title: SUPER THIN/SUPER THERMAL BALL GRID ARRAY PACKAGE
Chain of Title: From: Camenforte et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011883/0196

STATEMENT UNDER 37 CFR 3.73(b)

11. ☐
Inventor: John Briar
Serial No.: 09/640,534 Filing Date: 8/17/2000
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE
STRUCTURE
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011147/0398
12. ☐
Inventor: John Briar
Serial No.: 10/693,217 Filing Date: 10/24/2003
Title: FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE
STRUCTURE
Chain of Title: From: Briar To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011147/0398
13. ☐
Inventors: Raymundo M. Camenforte and John Briar
Serial No.: 10/371,515 Filing Date: 2/20/2003
Title: SINGLE UNIT AUTOMATED ASSEMBLY OF FLEX ENHANCED
GRID ARRAY PACKAGES
Chain of Title: From: Camenforte et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011310/0481
14. ☐
Inventors: Weddie Racio Aquien, John Briar, and Setho Sing Fee
Serial No.: 10/323,447 Filing Date: 12/19/2002
Title: ENHANCED BGA GROUNDED HEATSINK
Chain of Title: From: Aquien et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011793/0768
15. ☐
Inventor: Loreto Y. Cantillep
Serial No.: 10/236,579 Filing Date: 9/6/2002
Title: PBGA SINGULATED SUBSTRATE FOR MODEL MELAMINE
CLEANING
Chain of Title: From: Cantillep To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 011125/0469
16. ☐
Inventors: Jeffrey D. Punzalan, Tan Hien Boon, Zheng Zheng, Jae Hak Yee, and
Byung Joon Han
Serial No.: 10/462,264 Filing Date: 6/16/2003
Title: GROUND PLANE FOR EXPOSED PACKAGE
Chain of Title: From: Punzalan et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012656/0753

STATEMENT UNDER 37 CFR 3.73(b)

17. ☐

Inventors: IL Kwon Shim, Hermes T. Apale, and Gerry Balanon
Serial No.: 10/119,920 Filing Date: 4/10/2002
Title: HEAT SPREADER INTERCONNECT METHODOLOGY FOR
THERMALLY ENHANCED PBGA PACKAGES
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012791/0604

18. ☐

Inventor: Jian Jun Li
Serial No.: 10/224,151 Filing Date: 8/20/2002
Title: TEST COUPON PATTERN DESIGN TO CONTROL MULTILAYER
SAW SINGULATED PLASTIC BALL GRID ARRAY SUBSTRATE
MIS-REGISTRATION
Chain of Title: From: Li To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 013218/0397

19. ☐

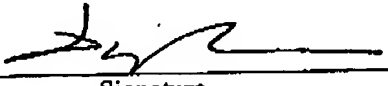
Inventors: Yong Gang Jin and Won Sun Shin
Serial No.: 10/151,977 Filing Date: 5/21/2002
Title: TORCH BUMP
Chain of Title: From: Jin et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 012923/0359

20. ☐

Inventors: IL Kwon Shim, Jian Jun Li, and Sheila Marie L. Alvarez
Serial No.: 10/279,900 Filing Date: 10/24/2002
Title: COST EFFECTIVE SUBSTRATE FABRICATION FOR FILP-CHIP
PACKAGES
Chain of Title: From: Shim et al. To: ST Assembly Test Services Pte Ltd
Recorded in the Patent and Trademark Office at reel/frame: 013434/0473

The undersigned (whose title is supplied below) is empowered to sign below on behalf of the assignee.

February 3, 2004
Date


Signature

Tan Lay Koon

Typed or printed name

President & CEO

Title